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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Not For New Designs
Core Processor	CIP-51 8051
Core Size	8-Bit
Speed	50MHz
Connectivity	I ² C, SMBus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	21
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	<u>.</u>
RAM Size	4.25K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	A/D 13x10/12b SAR; D/A 4x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	24-SSOP (0.154", 3.90mm Width)
Supplier Device Package	24-QSOP
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm8bb31f64g-b-qsop24r

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

3. System Overview

3.1 Introduction

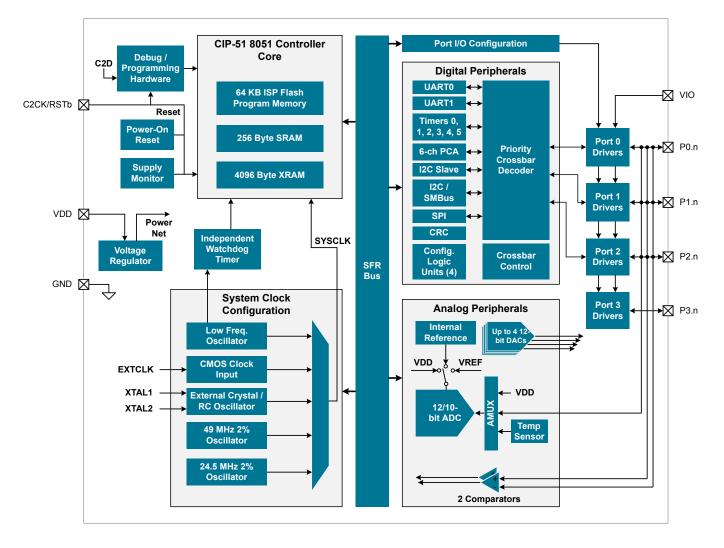


Figure 3.1. Detailed EFM8BB3 Block Diagram

Universal Asynchronous Receiver/Transmitter (UART1)

UART1 is an asynchronous, full duplex serial port offering a variety of data formatting options. A dedicated baud rate generator with a 16-bit timer and selectable prescaler is included, which can generate a wide range of baud rates. A received data FIFO allows UART1 to receive multiple bytes before data is lost and an overflow occurs.

UART1 provides the following features:

- · Asynchronous transmissions and receptions
- Dedicated baud rate generator supports baud rates up to SYSCLK/2 (transmit) or SYSCLK/8 (receive)
- 5, 6, 7, 8, or 9 bit data
- Automatic start and stop generation
- Automatic parity generation and checking
- · Single-byte buffer on transmit and receive
- Auto-baud detection
- · LIN break and sync field detection
- CTS / RTS hardware flow control

Serial Peripheral Interface (SPI0)

The serial peripheral interface (SPI) module provides access to a flexible, full-duplex synchronous serial bus. The SPI can operate as a master or slave device in both 3-wire or 4-wire modes, and supports multiple masters and slaves on a single SPI bus. The slave-select (NSS) signal can be configured as an input to select the SPI in slave mode, or to disable master mode operation in a multi-master environment, avoiding contention on the SPI bus when more than one master attempts simultaneous data transfers. NSS can also be configured as a firmware-controlled chip-select output in master mode, or disable to reduce the number of pins required. Additional general purpose port I/O pins can be used to select multiple slave devices in master mode.

- Supports 3- or 4-wire master or slave modes
- · Supports external clock frequencies up to 12 Mbps in master or slave mode
- · Support for all clock phase and polarity modes
- 8-bit programmable clock rate (master)
- Programmable receive timeout (slave)
- · Two byte FIFO on transmit and receive
- · Can operate in suspend or snooze modes and wake the CPU on reception of a byte
- · Support for multiple masters on the same data lines

System Management Bus / I2C (SMB0)

The SMBus I/O interface is a two-wire, bi-directional serial bus. The SMBus is compliant with the System Management Bus Specification, version 1.1, and compatible with the I²C serial bus.

The SMBus module includes the following features:

- · Standard (up to 100 kbps) and Fast (400 kbps) transfer speeds
- · Support for master, slave, and multi-master modes
- Hardware synchronization and arbitration for multi-master mode
- · Clock low extending (clock stretching) to interface with faster masters
- · Hardware support for 7-bit slave and general call address recognition
- Firmware support for 10-bit slave address decoding
- · Ability to inhibit all slave states
- Programmable data setup/hold times
- · Transmit and receive FIFOs (one byte) to help increase throughput in faster applications

Low Current Comparators (CMP0, CMP1)

An analog comparator is used to compare the voltage of two analog inputs, with a digital output indicating which input voltage is higher. External input connections to device I/O pins and internal connections are available through separate multiplexers on the positive and negative inputs. Hysteresis, response time, and current consumption may be programmed to suit the specific needs of the application.

The comparator includes the following features:

- · Up to 10 (CMP0) or 9 (CMP1) external positive inputs
- · Up to 10 (CMP0) or 9 (CMP1) external negative inputs
- · Additional input options:
 - Internal connection to LDO output
 - Direct connection to GND
 - Direct connection to VDD
 - · Dedicated 6-bit reference DAC
- Synchronous and asynchronous outputs can be routed to pins via crossbar
- Programmable hysteresis between 0 and ±20 mV
- · Programmable response time
- · Interrupts generated on rising, falling, or both edges
- · PWM output kill feature

3.8 Reset Sources

Reset circuitry allows the controller to be easily placed in a predefined default condition. On entry to this reset state, the following occur:

- The core halts program execution.
- · Module registers are initialized to their defined reset values unless the bits reset only with a power-on reset.
- · External port pins are forced to a known state.
- Interrupts and timers are disabled.

All registers are reset to the predefined values noted in the register descriptions unless the bits only reset with a power-on reset. The contents of RAM are unaffected during a reset; any previously stored data is preserved as long as power is not lost. By default, the Port I/O latches are reset to 1 in open-drain mode, with weak pullups enabled during and after the reset. Optionally, firmware may configure the port I/O, DAC outputs, and precision reference to maintain state through system resets other than power-on resets. For Supply Monitor and power-on resets, the RSTb pin is driven low until the device exits the reset state. On exit from the reset state, the program counter (PC) is reset, and the system clock defaults to an internal oscillator. The Watchdog Timer is enabled, and program execution begins at location 0x0000.

Reset sources on the device include the following:

- Power-on reset
- · External reset pin
- · Comparator reset
- Software-triggered reset
- Supply monitor reset (monitors VDD supply)
- · Watchdog timer reset
- · Missing clock detector reset
- · Flash error reset

3.9 Debugging

The EFM8BB3 devices include an on-chip Silicon Labs 2-Wire (C2) debug interface to allow flash programming and in-system debugging with the production part installed in the end application. The C2 interface uses a clock signal (C2CK) and a bi-directional C2 data signal (C2D) to transfer information between the device and a host system. See the C2 Interface Specification for details on the C2 protocol.

Device Package	Pin for Bootload Mode Entry
QFN32	P3.7 / C2D
QFP32	P3.7 / C2D
QFN24	P3.0 / C2D
QSOP24	P3.0 / C2D

Table 3.3. Summary of Pins for Bootload Mode Entry

4. Electrical Specifications

4.1 Electrical Characteristics

All electrical parameters in all tables are specified under the conditions listed in Table 4.1 Recommended Operating Conditions on page 14, unless stated otherwise.

Table 4.1. Recommended Operating Conditions

4.1.1 Recommended Operating Conditions

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Operating Supply Voltage on VDD	V _{DD}		2.2	_	3.6	V
Operating Supply Voltage on VIO ^{2,} 3	V _{IO}		2.2	_	V _{DD}	V
System Clock Frequency	f _{SYSCLK}		0	_	50	MHz
Operating Ambient Temperature	T _A	G-grade devices	-40	_	85	°C
		I-grade devices	-40	_	125	°C

Note:

1. All voltages with respect to GND

2. In certain package configurations, the VIO and VDD supplies are bonded to the same pin.

3. GPIO levels are undefined whenever VIO is less than 1 V.

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Stop Mode—Core halted and all clocks stopped,Internal LDO On, Supply monitor off.	I _{DD}		_	120	740	μA
Shutdown Mode—Core halted and all clocks stopped,Internal LDO Off, Supply monitor off.	I _{DD}		_	0.2	4.5	μA
Analog Peripheral Supply Curren	ts (-40 °C to	o +125 °C)			1	1
High-Frequency Oscillator 0	I _{HFOSC0}	Operating at 24.5 MHz, T _A = 25 °C	_	120	135	μA
High-Frequency Oscillator 1	I _{HFOSC1}	Operating at 49 MHz, T _A = 25 °C	_	770	1200	μA
Low-Frequency Oscillator	I _{LFOSC}	Operating at 80 kHz, T _A = 25 °C	_	3.7	6	μA
ADC0 ⁴	I _{ADC}	High Speed Mode 1 Msps, 10-bit conversions Normal bias settings V _{DD} = 3.0 V	_	1210	1600	μA
		Low Power Mode 350 ksps, 12-bit conversions Low power bias settings V _{DD} = 3.0 V	-	415	560	μA
Internal ADC0 Reference ⁵	I _{VREFFS}	High Speed Mode	_	700	790	μA
		Low Power Mode		170	210	μA
On-chip Precision Reference	I _{VREFP}		—	75	_	μA
Temperature Sensor	I _{TSENSE}		—	68	120	μA
Digital-to-Analog Converters (DAC0, DAC1, DAC2, DAC3) ⁶	I _{DAC}		_	125	_	μA
Comparators (CMP0, CMP1)	I _{CMP}	CPMD = 11	_	0.5	_	μA
		CPMD = 10	—	3	_	μA
		CPMD = 01	_	10	_	μA
		CPMD = 00	—	25	_	μA
Comparator Reference	I _{CPREF}		—	24	_	μA
Voltage Supply Monitor (VMON0)	I _{VMON}		_	15	20	μA

4.1.13 Comparators

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Response Time, CPMD = 00	t _{RESP0}	+100 mV Differential	_	100	_	ns
(Highest Speed)		-100 mV Differential	_	150	_	ns
Response Time, CPMD = 11 (Low-	t _{RESP3}	+100 mV Differential	_	1.5	_	μs
est Power)		-100 mV Differential	—	3.5	_	μs
Positive Hysteresis	HYS _{CP+}	CPHYP = 00	_	0.4	_	mV
Mode 0 (CPMD = 00)		CPHYP = 01	_	8	_	mV
		CPHYP = 10	_	16	_	mV
		CPHYP = 11	_	32	_	mV
Negative Hysteresis	HYS _{CP-}	CPHYN = 00	_	-0.4	_	mV
Mode 0 (CPMD = 00)		CPHYN = 01	_	-8	_	mV
		CPHYN = 10	_	-16	_	mV
		CPHYN = 11	_	-32	_	mV
Positive Hysteresis	HYS _{CP+}	CPHYP = 00	_	0.5	_	mV
Mode 1 (CPMD = 01)		CPHYP = 01	—	6	_	mV
		CPHYP = 10	_	12	_	mV
		CPHYP = 11	_	24	_	mV
Negative Hysteresis	HYS _{CP-}	CPHYN = 00	_	-0.5	_	mV
Mode 1 (CPMD = 01)		CPHYN = 01	_	-6	_	mV
		CPHYN = 10	—	-12	_	mV
		CPHYN = 11	—	-24	_	mV
Positive Hysteresis	HYS _{CP+}	CPHYP = 00	_	0.7	_	mV
Mode 2 (CPMD = 10)		CPHYP = 01	_	4.5	_	mV
		CPHYP = 10	_	9	_	mV
		CPHYP = 11	_	18	_	mV
Negative Hysteresis	HYS _{CP-}	CPHYN = 00	_	-0.6	_	mV
Mode 2 (CPMD = 10)		CPHYN = 01	_	-4.5	_	mV
		CPHYN = 10	_	-9	_	mV
		CPHYN = 11	_	-18	_	mV
Positive Hysteresis	HYS _{CP+}	CPHYP = 00	_	1.5	_	mV
Mode 3 (CPMD = 11)		CPHYP = 01		4	_	mV
		CPHYP = 10	_	8	_	mV
		CPHYP = 11		16	_	mV

Table 4.13. Comparators

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Negative Hysteresis	HYS _{CP-}	CPHYN = 00	_	-1.5	_	mV
Mode 3 (CPMD = 11)		CPHYN = 01	_	-4	_	mV
		CPHYN = 10	_	-8	_	mV
		CPHYN = 11	—	-16	—	mV
Input Range (CP+ or CP-)	V _{IN}		-0.25	_	V _{IO} +0.25	V
Input Pin Capacitance	C _{CP}		—	7.5	—	pF
Internal Reference DAC Resolution	N _{bits}			6	1	bits
Common-Mode Rejection Ratio	CMRR _{CP}		_	70	_	dB
Power Supply Rejection Ratio	PSRR _{CP}		_	72	_	dB
Input Offset Voltage	V _{OFF}	T _A = 25 °C	-10	0	10	mV
Input Offset Tempco	TC _{OFF}		_	3.5	_	μV/°

4.1.14 Configurable Logic

Table 4.14. Configurable Logic

Parameter	Symbol	Test Condition	Min	Тур	Мах	Unit
Propagation Delay	t _{DLY}	Through single CLU	—	_	35.3	ns
		Using an external pin				
		Through single CLU	—	3	—	ns
		Using an internal connection				
Clocking Frequency	F _{CLK}	1 or 2 CLUs Cascaded	—	—	73.5	MHz
		3 or 4 CLUs Cascaded			36.75	MHz

5. Typical Connection Diagrams

5.1 Power

Figure 5.1 Power Connection Diagram on page 33 shows a typical connection diagram for the power pins of the device.

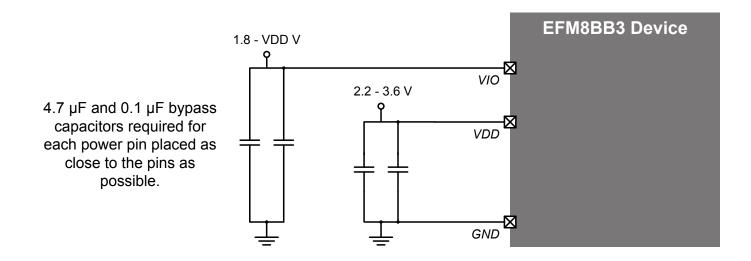


Figure 5.1. Power Connection Diagram

5.2 Debug

The diagram below shows a typical connection diagram for the debug connections pins. The pin sharing resistors are only required if the functionality on the C2D (a GPIO pin) and the C2CK (RSTb) is routed to external circuitry. For example, if the RSTb pin is connected to an external switch with debouncing filter or if the GPIO sharing with the C2D pin is connected to an external circuit, the pin sharing resistors and connections to the debug adapter must be placed on the hardware. Otherwise, these components and connections can be omitted.

For more information on debug connections, see the example schematics and information available in AN127: "Pin Sharing Techniques for the C2 Interface." Application notes can be found on the Silicon Labs website (http://www.silabs.com/8bit-appnotes) or in Simplicity Studio.

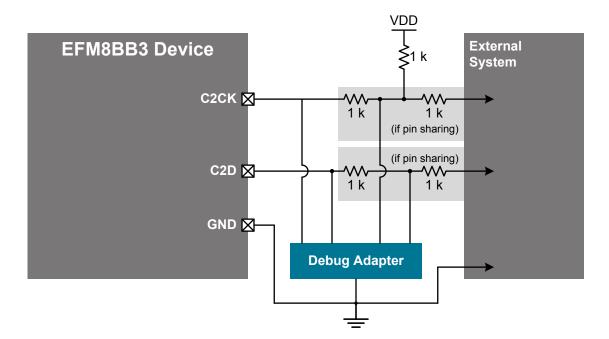


Figure 5.2. Debug Connection Diagram

5.3 Other Connections

Other components or connections may be required to meet the system-level requirements. Application Note AN203: "8-bit MCU Printed Circuit Board Design Notes" contains detailed information on these connections. Application Notes can be accessed on the Silicon Labs website (www.silabs.com/8bit-appnotes).

6. Pin Definitions

6.1 EFM8BB3x-QFN32 Pin Definitions

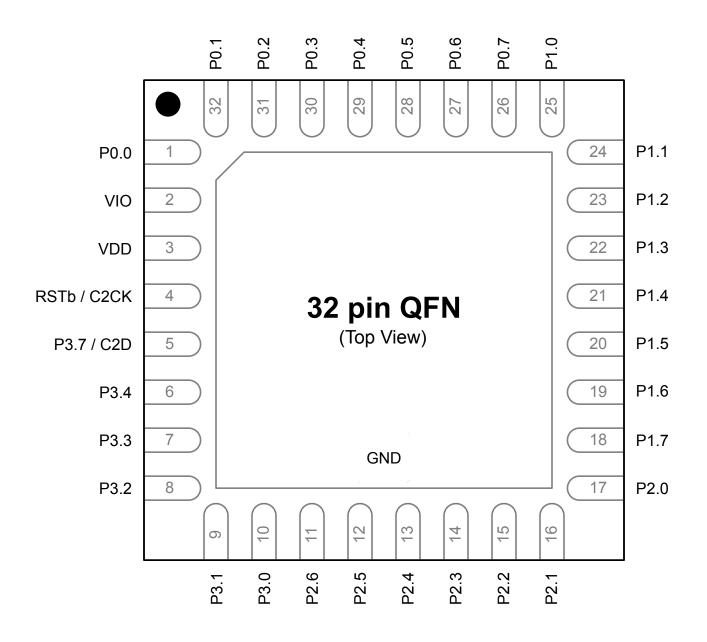


Figure 6.1. EFM8BB3x-QFN32 Pinout

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
18	P1.7	Multifunction I/O	Yes	P1MAT.7	ADC0.13
				CLU0B.15	CMP0P.9
				CLU1B.13	CMP0N.9
				CLU2A.13	
19	P1.6	Multifunction I/O	Yes	P1MAT.6	ADC0.12
				CLU0A.15	
				CLU1B.12	
				CLU2A.12	
20	P1.5	Multifunction I/O	Yes	P1MAT.5	ADC0.11
				CLU0B.14	
				CLU1A.13	
				CLU2B.13	
21	P1.4	Multifunction I/O	Yes	P1MAT.4	ADC0.10
				CLU0A.14	
				CLU1A.12	
				CLU2B.12	
22	P1.3	Multifunction I/O	Yes	P1MAT.3	ADC0.9
				CLU0B.13	
				CLU1B.11	
				CLU2B.11	
				CLU3A.13	
23	P1.2	Multifunction I/O	Yes	P1MAT.2	ADC0.8
				CLU0A.13	CMP0P.8
				CLU1A.11	CMP0N.8
				CLU2B.10	
				CLU3A.12	
24	P1.1	Multifunction I/O	Yes	P1MAT.1	ADC0.7
				CLU0B.12	CMP0P.7
				CLU1B.10	CMP0N.7
				CLU2A.11	
				CLU3B.13	

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
25	P1.0	Multifunction I/O	Yes	P1MAT.0	ADC0.6
				CLU1OUT	CMP0P.6
				CLU0A.12	CMP0N.6
				CLU1A.10	CMP1P.1
				CLU2A.10	CMP1N.1
				CLU3B.12	
26	P0.7	Multifunction I/O	Yes	P0MAT.7	ADC0.5
				INT0.7	CMP0P.5
				INT1.7	CMP0N.5
				CLU0B.11	CMP1P.0
				CLU1B.9	CMP1N.0
				CLU3A.11	
27	P0.6	Multifunction I/O	Yes	P0MAT.6	ADC0.4
				CNVSTR	CMP0P.4
				INT0.6	CMP0N.4
				INT1.6	
				CLU0A.11	
				CLU1B.8	
				CLU3A.10	
28	P0.5	Multifunction I/O	Yes	P0MAT.5	ADC0.3
				INT0.5	CMP0P.3
				INT1.5	CMP0N.3
				UART0_RX	
				CLU0B.10	
				CLU1A.9	
				CLU3B.11	
29	P0.4	Multifunction I/O	Yes	P0MAT.4	ADC0.2
				INT0.4	CMP0P.2
				INT1.4	CMP0N.2
				UART0_TX	
				CLU0A.10	
				CLU1A.8	
				CLU3B.10	

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
24	P0.2	Multifunction I/O	Yes	P0MAT.2	XTAL1
				INT0.2	ADC0.1
				INT1.2	CMP0P.1
				CLU0OUT	CMP0N.1
				CLU0A.9	
				CLU2B.8	
				CLU3A.8	
Center	GND	Ground			

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
11	P2.1	Multifunction I/O	Yes	P2MAT.1	DAC1
				CLU1B.14	
				CLU2A.15	
				CLU3B.15	
12	P2.0	Multifunction I/O	Yes	P2MAT.0	DAC0
				CLU1A.14	
				CLU2A.14	
				CLU3B.14	
13	P1.7	Multifunction I/O	Yes	P1MAT.7	ADC0.12
				CLU0B.15	CMP1P.6
				CLU1B.13	CMP1N.6
				CLU2A.13	
14	P1.6	Multifunction I/O	Yes	P1MAT.6	ADC0.11
				CLU3OUT	CMP1P.5
				CLU0A.15	CMP1N.5
				CLU1B.12	
				CLU2A.12	
15	P1.5	Multifunction I/O	Yes	P1MAT.5	ADC0.10
				CLU2OUT	CMP1P.4
				CLU0B.14	CMP1N.4
				CLU1A.13	
				CLU2B.13	
16	P1.4	Multifunction I/O	Yes	P1MAT.4	ADC0.9
				I2C0_SCL	CMP1P.3
				CLU0A.14	CMP1N.3
				CLU1A.12	
				CLU2B.12	
17	P1.3	Multifunction I/O	Yes	P1MAT.3	CMP1P.2
				I2C0_SDA	CMP1N.2
				CLU0B.13	
				CLU1B.11	
				CLU2B.11	
				CLU3A.13	

Pin Number	Pin Name	Description	Crossbar Capability	Additional Digital Functions	Analog Functions
18	P1.2	Multifunction I/O	Yes	P1MAT.2	ADC0.8
				CLU0A.13	
				CLU1A.11	
				CLU2B.10	
				CLU3A.12	
19	P1.1	Multifunction I/O	Yes	P1MAT.1	ADC0.7
				CLU0B.12	
				CLU1B.10	
				CLU2A.11	
				CLU3B.13	
20	P1.0	Multifunction I/O	Yes	P1MAT.0	ADC0.6
				CLU0A.12	
				CLU1A.10	
				CLU2A.10	
				CLU3B.12	
21	P0.7	Multifunction I/O	Yes	P0MAT.7	ADC0.5
				INT0.7	CMP0P.5
				INT1.7	CMP0N.5
				CLU1OUT	CMP1P.1
				CLU0B.11	CMP1N.1
				CLU1B.9	
				CLU3A.11	
22	P0.6	Multifunction I/O	Yes	P0MAT.6	ADC0.4
				CNVSTR	CMP0P.4
				INT0.6	CMP0N.4
				INT1.6	CMP1P.0
				CLU0A.11	CMP1N.0
				CLU1B.8	
				CLU3A.10	
23	P0.5	Multifunction I/O	Yes	P0MAT.5	ADC0.3
				INT0.5	CMP0P.3
				INT1.5	CMP0N.3
				UART0_RX	
				CLU0B.10	
				CLU1A.9	
				CLU3B.11	

7. QFN32 Package Specifications

7.1 QFN32 Package Dimensions

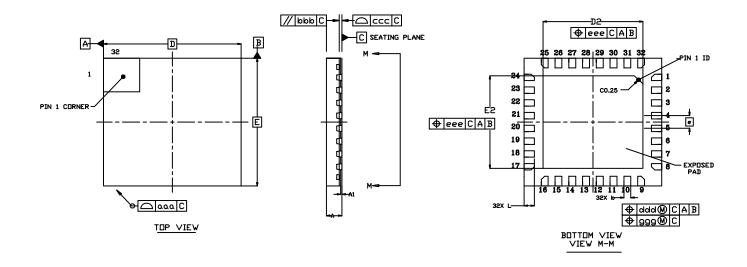


Figure 7.1. QFN32 Package Drawing

Dimension	Min	Тур	Мах
A	0.45	0.50	0.55
A1	0.00	0.035	0.05
b	0.15	0.20	0.25
D	4.00 BSC.		
D2	2.80	2.90	3.00
e	0.40 BSC.		
E	4.00 BSC.		
E2	2.80	2.90	3.00
L	0.20	0.30	0.40
ааа	_	_	0.10
bbb	—	_	0.10
ссс	—	_	0.08
ddd	_	_	0.10
eee	—	—	0.10
999	_	_	0.05

Table 7.1. QFN32 Package Dimensions

8. QFP32 Package Specifications

8.1 QFP32 Package Dimensions

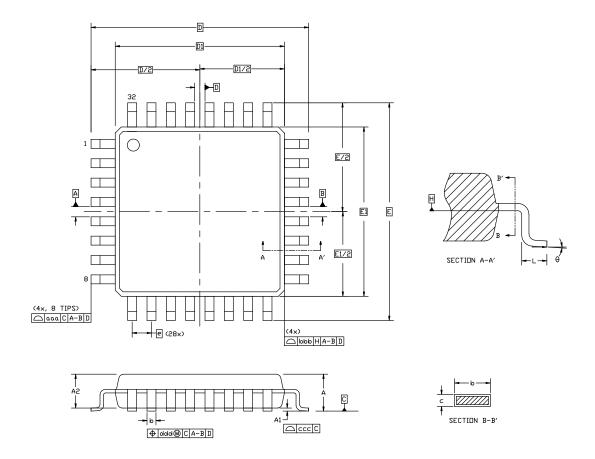


Figure 8.1. QFP32 Package Drawing

Table 8.1. QFP32 Package Dimensions

Dimension	Min	Тур	Мах
A	_		1.20
A1	0.05	—	0.15
A2	0.95	1.00	1.05
b	0.30	0.37	0.45
С	0.09	_	0.20
D	9.00 BSC		
D1	7.00 BSC		
е	0.80 BSC		
E	9.00 BSC		
E1	7.00 BSC		
L	0.50	0.60	0.70



Figure 10.3. QSOP24 Package Marking

The package marking consists of:

- PPPPPPP The part number designation.
- TTTTTT A trace or manufacturing code.
- YY The last 2 digits of the assembly year.
- WW The 2-digit workweek when the device was assembled.
- # The device revision (A, B, etc.).

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